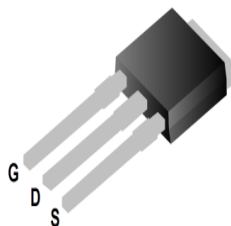
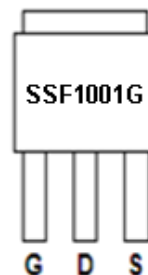
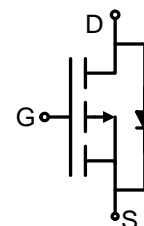


Main Product Characteristics:

V_{DSS}	-100V
$R_{DS(on)}$	75m Ω (typ.)
I_D	-25A



TO-251 (IPAK)


 Marking and pin
Assignment


Schematic diagram

Features and Benefits:

- Advanced MOSFET process technology
- Special designed for PWM, load switching and general purpose applications
- Ultra low on-resistance with low gate charge
- Fast switching and reverse body recovery
- 150°C operating temperature


Description:

It utilizes the latest processing techniques to achieve the high cell density and reduces the on-resistance with high repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in power switching application and a wide variety of other applications.

Absolute max Rating:

Symbol	Parameter	Max.	Units
I_D @ TC = 25°C	Continuous Drain Current, V_{GS} @ -10V ①	-25	A
I_{DM}	Pulsed Drain Current ②	-100	
P_D @TC = 25°C	Power Dissipation ③	73.5	W
V_{DS}	Drain-Source Voltage	-100	V
V_{GS}	Gate-to-Source Voltage	± 25	V
E_{AS}	Single Pulse Avalanche Energy @ L=0.1mH	36.5	mJ
I_{AS}	Avalanche Current @ L=0.1mH	27	A
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	°C

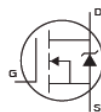
Thermal Resistance

Symbol	Characterizes	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-case ^③	—	1.7	$^{\circ}C/W$
$R_{\theta JA}$	Junction-to-ambient ($t \leq 10s$) ^④	—	62	$^{\circ}C/W$

Electrical Characterizes @ $T_A=25^{\circ}C$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source breakdown voltage	-100	—	—	V	$V_{GS} = 0V, I_D = -250\mu A$
$R_{DS(on)}$	Static Drain-to-Source on-resistance	—	75	95	m Ω	$V_{GS}=-10V, I_D=-8A$
		—	83	110		$V_{GS}=-4.5V, I_D=-3A$
$V_{GS(th)}$	Gate threshold voltage	-1	—	-3	V	$V_{DS} = V_{GS}, I_D = -250\mu A$
I_{DSS}	Drain-to-Source leakage current	—	—	-1	μA	$V_{DS} = -100V, V_{GS} = 0V$
I_{GSS}	Gate-to-Source forward leakage	—	—	100	nA	$V_{GS} = 25V$
		—	—	-100		$V_{GS} = -25V$
Q_g	Total gate charge	—	40.4	—	nC	$I_D = -6A,$ $V_{DS} = -50V,$ $V_{GS} = -10V$
Q_{gs}	Gate-to-Source charge	—	7.7	—		
Q_{gd}	Gate-to-Drain("Miller") charge	—	6.6	—		
$t_{d(on)}$	Turn-on delay time	—	30	—	ns	$V_{GS} = -10V, V_{DS} = -30V,$ $R_{GEN} = 6\Omega$ $I_D = -1A$
t_r	Rise time	—	15	—		
$t_{d(off)}$	Turn-Off delay time	—	160	—		
t_f	Fall time	—	50	—		
C_{iss}	Input capacitance	—	3230	—	pF	$V_{GS} = 0V$ $V_{DS} = -50V$ $f = 1MHz$
C_{oss}	Output capacitance	—	113	—		
C_{riss}	Reverse transfer capacitance	—	67	—		

Source-Drain Ratings and Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	-25	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode)	—	—	-100	A	
V_{SD}	Diode Forward Voltage	—	—	-1.2	V	$I_S = -6A, V_{GS} = 0V$

Test circuits and Waveforms

EAS Test Circuit:

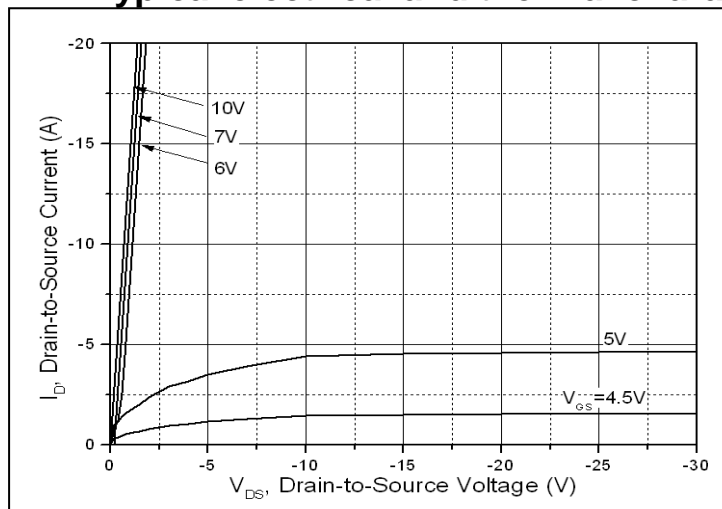
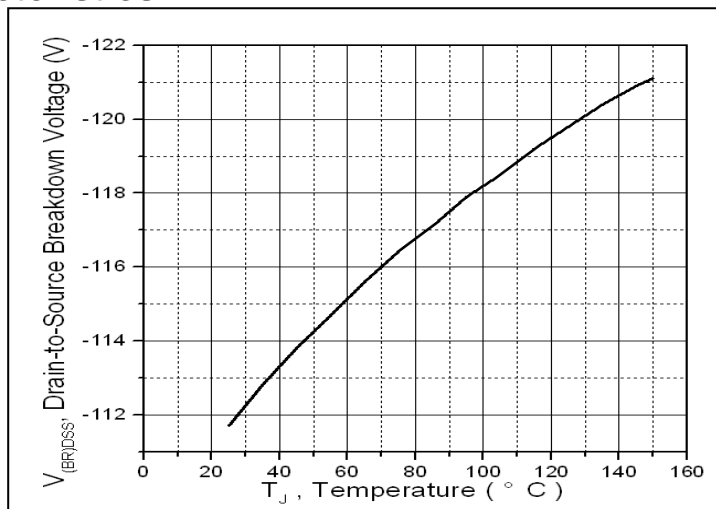
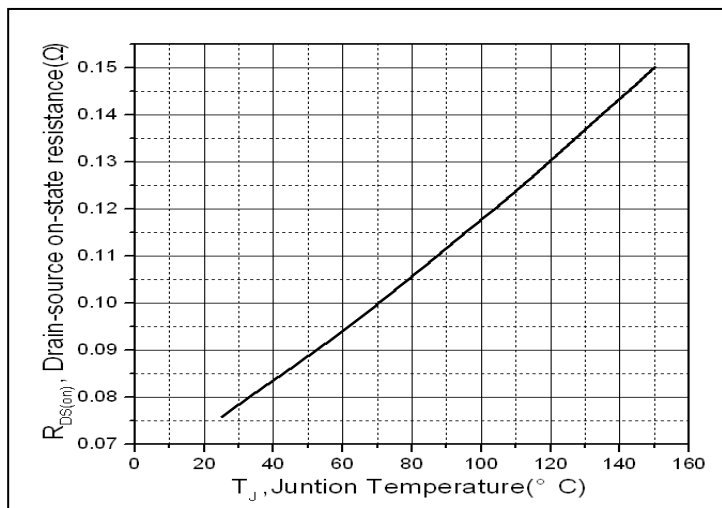
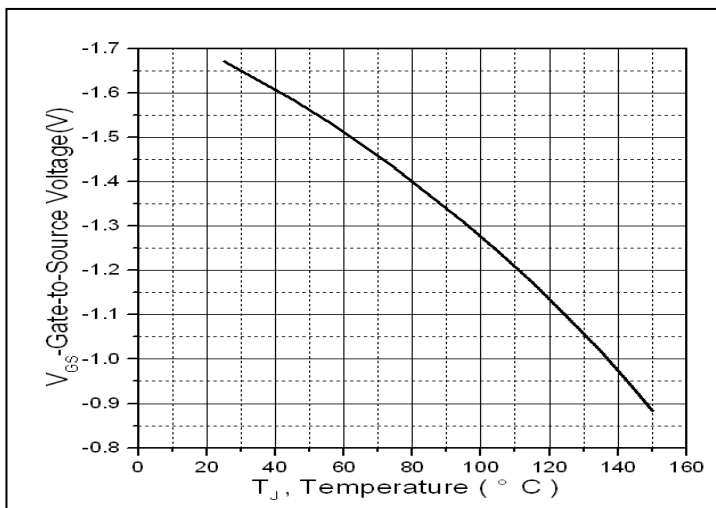
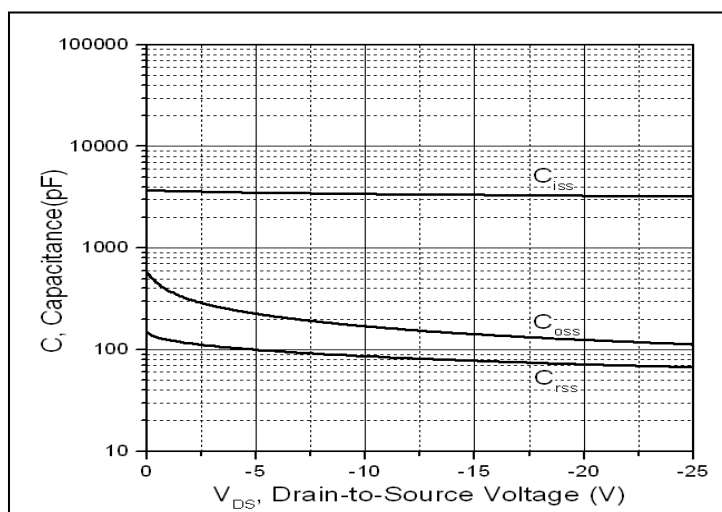
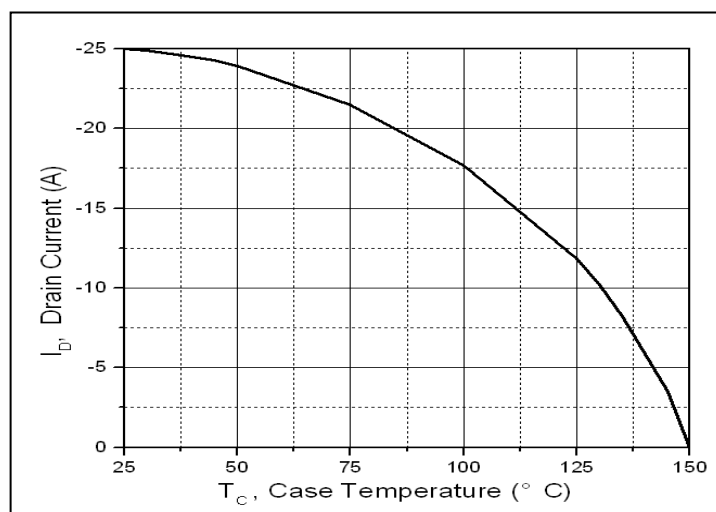
Gate charge test circuit:

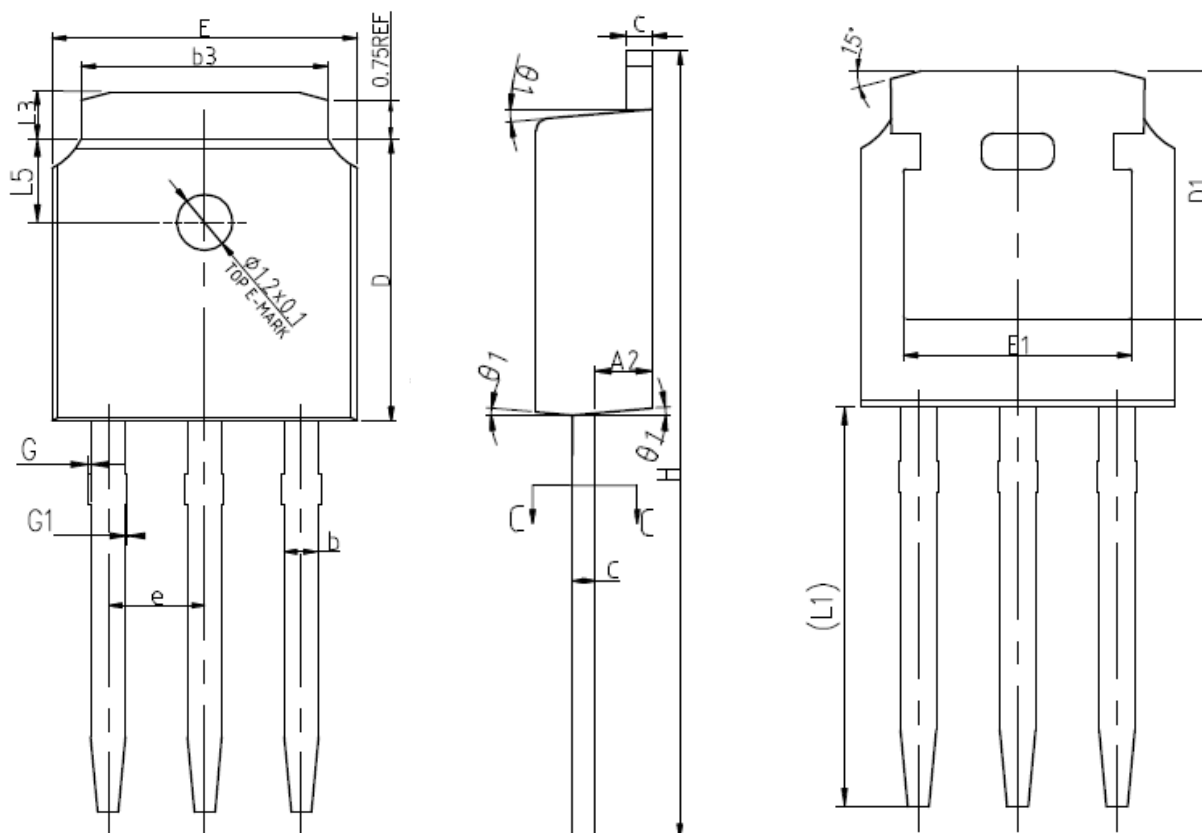
Switching Time Test Circuit:

Switching Waveforms:

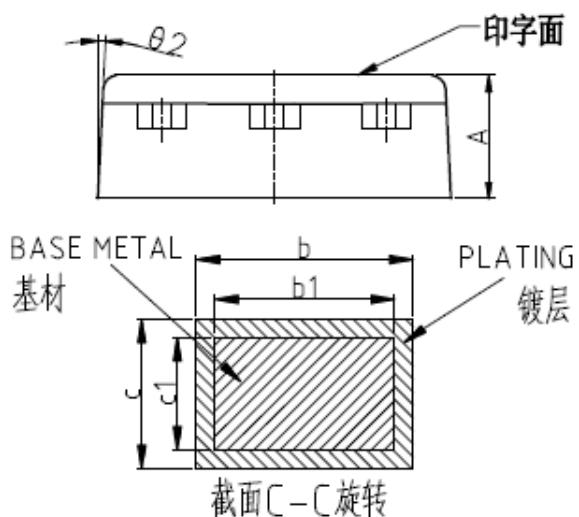

Notes:

- ① Calculated continuous current based on maximum allowable junction temperature.
- ② Repetitive rating; pulse width limited by max. junction temperature.
- ③ The power dissipation PD is based on max. junction temperature, using junction-to-case thermal resistance.
- ④ The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$

Typical electrical and thermal characteristics

Figure 1: Typical Output Characteristics

Figure 2: Drain-to-Source Breakdown Voltage vs. Temperature

Figure 3: Normalized On-Resistance Vs. Case Temperature

Figure 4: Gate to source cut-off voltage

Figure 5: Typical Capacitance Vs. Drain-to-Source Voltage

Figure 6: Maximum Drain Current Vs. Case Temperature

Mechanical Data:


COMMON DIMENSIONS



SYMBOL	MM		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A2	0.97	1.07	1.17
b	0.72	0.78	0.85
b1	0.71	0.76	0.81
b3	5.23	5.33	5.46
c	0.47	0.53	0.58
c1	0.46	0.51	0.56
D	6.00	6.10	6.20
D1	5.30REF		
E	6.50	6.60	6.70
E1	4.70	4.83	4.92
e	2.286BSC		
H	16.10	16.40	16.60
L1	9.20	9.40	9.60
L3	0.90	1.02	1.25
L5	1.70	1.80	1.90
$\theta 1$	5°	7°	9°
$\theta 2$	5°	7°	9°

NOTES
 1. ALL DIMENSIONS REFER TO JEDEC STANDARD TO-251 AA,
 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

Ordering and Marking Information
Device Marking: SSF1001G

Package (Available)
TO-251(IPAK)
Operating Temperature Range
C : -55 to 150 °C

Devices per Unit

Package Type	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO-251	75	40	3000	5	15000

Reliability Test Program

Test Item	Conditions	Duration	Sample Size
High Temperature Reverse Bias(HTRB)	T _j =125°C to 150°C @ 80% of Max V _{DSS} /V _{CES} /VR	168 hours 500 hours 1000 hours	3 lots x 77 devices
High Temperature Gate Bias(HTGB)	T _j =150°C @ 100% of Max V _{GSS}	168 hours 500 hours 1000 hours	3 lots x 77 devices

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